

SEMICONDUCTOR DEVICE

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Classification:

- **international:** H01L23/34; H01L23/50; H05K3/30; H05K3/34; H01L23/34;
H01L23/48; H05K3/30; H05K3/34; (IPC1-7): H01L23/34;
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- **European:**

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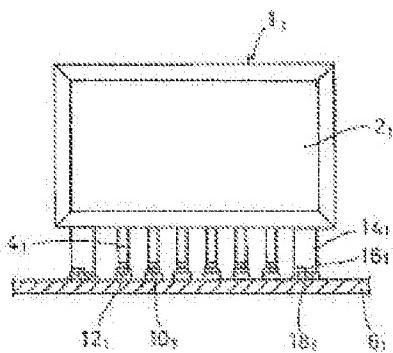
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Abstract of JP 5036888 (A)

PURPOSE: To enable a semiconductor device which is mounted upright on a board to be more enhanced in mounting density than usual.

CONSTITUTION: A support 141 electrically separate from outer leads 41 is erected extending outward from a resin-sealed part 21, and an outer fixing part 161 is provided to the end of the support 141.



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